

# SOT570-3

thin fine-pitch ball grid array package; 180 balls

8 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	B (bottom)
<b>Package type descriptive code</b>	TFBGA180
<b>Package type industry code</b>	TFBGA180
<b>Package style descriptive code</b>	TFBGA (thin fine-pitch ball grid array)
<b>Package style suffix code</b>	NA (not applicable)
<b>Package body material type</b>	P (plastic)
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	15-4-2010

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	11.9	-	12	12.1	mm
E	package width	11.9	-	12	12.1	mm
A	seated height	0.95	-	1.06	1.2	mm
A <sub>2</sub>	package height	0.65	-	0.71	0.8	mm
e	nominal pitch	-	-	0.8	-	mm
n <sub>2</sub>	actual quantity of termination	-	-	180	-	



## 2. Package outline

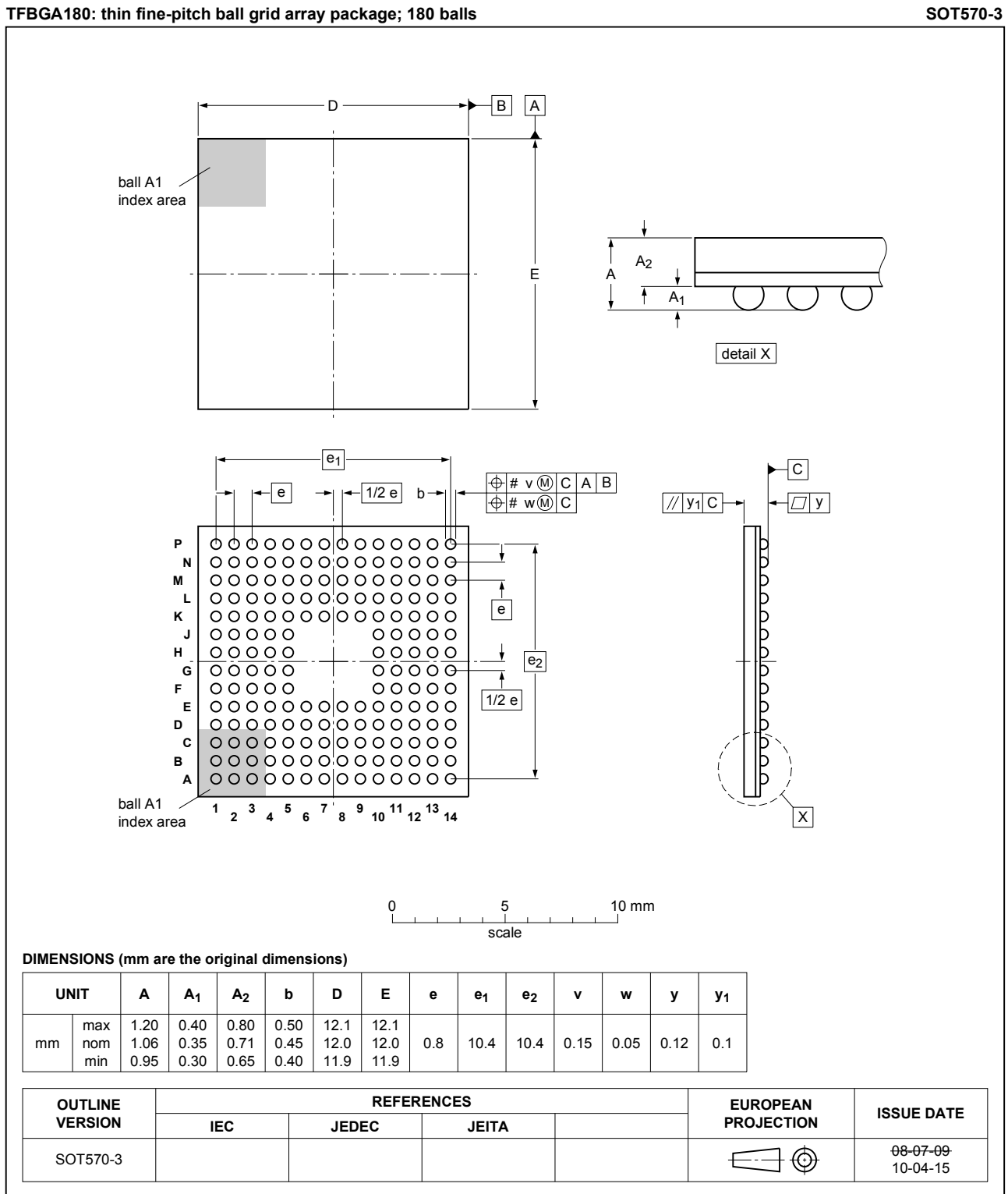


Fig. 1. Package outline TFBGA180 (SOT570-3)

### 3. Soldering

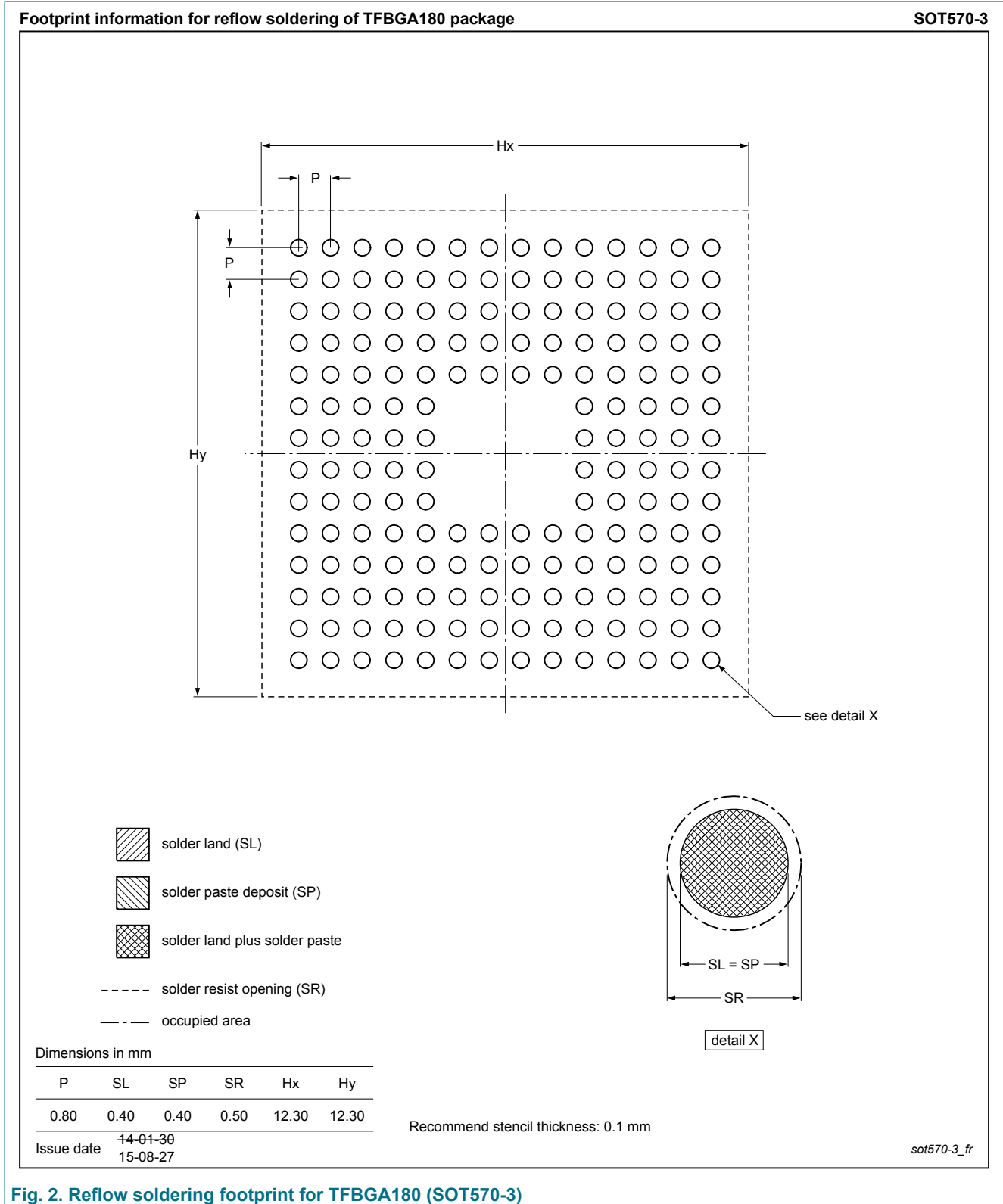


Fig. 2. Reflow soldering footprint for TFBGA180 (SOT570-3)

## 4. Legal information

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